Trion Mini-lock Phantom III REACTIVE ION ETCH with ICP

NCF's TRION Mini-lock-Phantom III ICP-RIE system comes with a vacuum load-lock that allows for isolation of the reaction chamber from atmosphere to reduce the impact of exposure to atmosphere between runs. With a 600 watt, 13.56 MHz solid state RF generator, users have the option of standard processing or inductively coupled plasma enhanced etching. The system can accommodate multiple wafers in a single run. After passing the NCF safety exam, users can request training on this machine by sending an email to ncftech@uic.edu. Those not trained can request an NCF work service order by contacting the lab manager.

Location: Clean room-deposition bay

Training: 3-5 sessions (Minimum training-2 trainings and a checkout session)

Technical Specifications:

- Wafer Sizes: 2, 3, and 4-inch
- Max ICP Power: 600 Watt with automatic matching network
- Min Pressure: 0 mTorr
- Gases: N_2 , O_2, Ar, SF_6, NF_3, $He - O_2$ $mixture$, CHF_3, CCl_2F_2, Cl_2, CF_4, $SiCl_4$